

# MATERIAL DECLARATION SHEET



Material Number	CR1206 Series			Picture attached 
Product Line	Thick Film Chip Resistors			
Compliance Date	2021/02/17			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	CRXXXX	7.78997	Aluminum oxide	1344-28-1	96%	87.04%	90.67%
				Silicon dioxide	14808-60-7	4%	3.63%	
2	Conductor Layer	AZZ.002.5421	0.14692	Silver	7440-22-4	95%	1.62%	1.71%
				Glass	65997-17-3	5%	0.09%	
3	Resistive Element	AZZ.002.00XXX	0.09537	Ruthenium(IV) oxide	12036-10-1	25%	0.28%	1.11%
				Silver	7440-22-4	40%	0.44%	
				Palladium	7440-05-3	15%	0.17%	
				Lead	7439-92-1	20%	0.22%	
4	Over Coating	AZZ.002.1057A	0.11341	Epoxy	25068-38-6	100%	1.32%	1.32%
5	Marking	ZSR-1XX	0.01289	Epoxy	25085-99-8	100%	0.15%	0.15%
6	End Terminal	AZZ.003.0048	0.00687	Nickel	7440-02-0	80%	0.06%	0.08%
				Chromium	7440-47-3	20%	0.02%	
7	Ni Plating	Ni	0.23197	Nickel	7440-02-0	100%	2.70%	2.70%
8	Sn Plating	Sn	0.19417	Tin	7440-31-5	100%	2.26%	2.26%
TOTAL WEIGHT			8.59156					

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This Document was updated on: 2021/02/17 ← the Date you completed fulfillment.

Important remarks: It is the responsibility of the user to verify they are accessing the latest version.